

In The Drawings

A new Figure 3A is attached hereto.

In The Specification

Page 12, after paragraph description for Figure 3, please add the following new paragraph:

B1
Figure 3A is an enlarged, cross-sectional view of another embodiment of the present invention electronic structure having a third insulating layer deposited on top.

Page 23, lines 1-17, has been amended as follows:

B2
In another embodiment of the present invention, more than one level of the electrically resistive vias may be formed and connected to each other. For instance, as shown in Figure 3A, a third insulating material layer 66 may be deposited overlying the second plurality of conductive elements and the second insulating material layer; and then a second plurality of electrically resistive vias that have a resistivity of at least 100 Ω -

cm may be formed in the third insulating material layer wherein each of the second plurality of conductive elements is in electrical communication with at least one of the second plurality of electrically resistive vias; and a third plurality of conductive elements is then formed on top of the third insulating material layer each in electrical communication with at least one of the second plurality of electrically resistive vias, whereby at least one of the second plurality of electrically resistive vias is in electrical communication with at least one of the first plurality of electrically resistive vias.

Cont'd
B2

REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.

A new Figure 3A is attached hereto for the Examiner's approval. The specification, in accordance with new Figure 3A, has been amended accordingly.